

Amendments to the Claims:

The following Listing of Claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims

1. (previously presented/withdrawn) A flexible mold prepared by the method of claim 11.

2-5. (cancelled)

6. (withdrawn) The flexible mold as defined in claim 1, wherein said groove pattern has a lattice like pattern constituted by a plurality of groove portions so arranged as to be substantially parallel with one another while crossing one another with predetermined gaps.

7. (currently amended) A method of manufacturing a microstructure having a projection pattern having a predetermined shape and a predetermined size on a surface of a substrate, comprising the steps of:

providing a flexible mold having a groove pattern having a shape and a size corresponding to those of said projection pattern on a surface thereof, and including a base layer made of a first curable~~[[ed]]~~ material having a viscosity of 3,000 to 100,000 cps at 10 to 80°C and a coating layer made of a second curable~~[[ed]]~~ material disposed on the surface of the base layer having a viscosity of not greater than 200 cps at 10 to 80°C;

arranging a curable rib precursor material between said substrate and said coating layer of said mold and filling said molding material into said groove pattern of said mold;

curing said molding material and forming a microstructure having said substrate and said projection pattern integrally bonded to said substrate; and

releasing said microstructure from said mold.

8. (previously presented) The manufacturing method as defined in claim 7, wherein said molding material is a photo-curable material.

9. (previously presented) The manufacturing method as defined in claim 7, wherein said microstructure is a back plate for a plasma display panel.

10. (previously presented) The manufacturing method as defined in claim 9, which further comprises a step of independently arranging a set of address electrodes substantially in parallel with each other while keeping a predetermined gap between them.

11. (previously presented) A method of making a flexible mold comprising:
coating a first curable material having a viscosity of 3,000 to 100,000 cps at 10 to 80°C on a support film;
coating a second curable material having a viscosity of not greater than 200 cps at 10 to 80°C on a master mold filling recesses of the mold;
laminating the coated support to the coated mold such that the first curable material is between the second curable material and the support film;
heat curing or photocuring the first and second curable material; and
releasing the flexible mold from the master mold.

12. (previously presented) The method of claim 11 wherein first curable material is photocurable.

13. (previously presented) The method of claim 12 wherein the first curable material contains a urethane acrylate oligomer, an epoxy acrylate oligomer, or a combination thereof.

14. (previously presented) The method of claim 11 wherein the second curable material is photocurable.

15. (previously presented) The method of claim 14 wherein the second curable material contains an acrylic monomer selected from the group consisting of acrylamide, acrylonitrile, acrylic acid, and acrylic acid ester.

16. (previously presented) The method of claim 11 wherein the first curable material and second curable material are photocurable.

17. (previously presented) The method of claim 16 wherein the support film is optically transparent such that rays of light irradiated for curing can transmit through the support film.

18. (previously presented) The method of claim 17 wherein the first curable material and second curable material are photocured through the support film.

19. (previously presented) The method of claim 7, wherein said flexible mold is suitable for making microstructures of a back plate for a plasma display panel.

20. (previously presented) The method of claim 11 wherein the rib precursor contains a ceramic component, a glass component, and a binder component.

21. (new) The method of claim 11 wherein the support film is flexible.

22. (new) The method of claim 11 wherein the support film is selected from the group consisting of polyethylene terephthalate, polyethylene naphthalate, and polycarbonate.

23. (new) The method of claim 11 wherein the support film has a thickness ranging from 50 to 500 μm .

24. (new) The method of claim 11 wherein during laminating the second curable material is replaced by the first curable material.